

Electronic Patent Application Fee Transmittal

Application Number:	10591455			
Filing Date:	18-Jan-2007			
Title of Invention:	THERMOPLASTIC RESIN COMPOSITION AND MOLDED ARTICLE COMPRISING THE SAME			
First Named Inventor/Applicant Name:	Hideo Aoki			
Filer:	Marvin Jay Spivak/Mimi Chanthaphone			
Attorney Docket Number:	295958US0PCT			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1510	1510
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Printed copy of patent - no color	8001	2	3	6
Total in USD (\$)				1816